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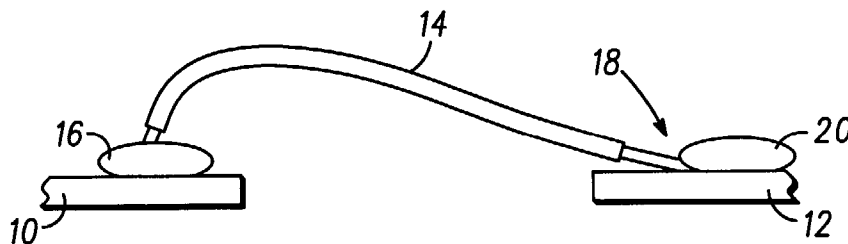
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(54) Title: WIREBONDING INSULATED WIRE



(57) Abstract: An electrical connection for connecting a bond pad of a first device and a bond pad of a second device with an insulated or coated wire. The electrical connection includes a first wirebond securing a first portion of the insulated bond wire to the first device bond pad. A second wirebond secures a second portion of the insulated bond wire to the second device bond pad. A bump is formed over the second wirebond, and the bump is offset from the second wirebond. The offset bump enhances the second bond, providing it with increased wire peel strength.

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